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TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

TFT Display Module

Part Number E50RG84885LWAM520-CA

Overview:

- 5.0-inch TFT (67.56x122.35mm)
- 3-SPI+16/18/24-bit RGB Interface
- 480(RGB)x854 pixels
- 3.3V
- White LED back-light

- Transmissive/ Normally Black
- Capacitive Touch Screen
- 430 NITS
- Controllers: ILI9806E, GT911
- RoHS Compliant



Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a transmissive type TFT-LCD Panel, driver circuit and backlight unit. The resolution of a 5.0" TFT-LCD contains 480x854 pixels and can display up to 65K/262K/16.7M colors.

Features

Low Input Voltage: 3.3V (TYP)

Display Colors of TFT LCD: 65K/262K/16.7M colors

TFT Interface: 3-SPI+16/18/24-bit RGB

CTP Interface: I2C

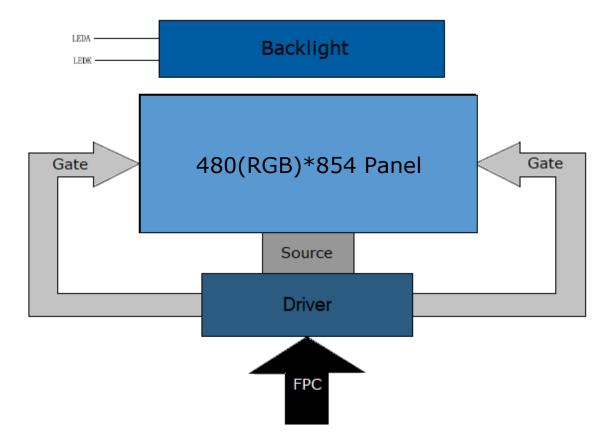
General Information Items	Specification	Unit	Note
	Main Panel		
TFT Display area (AA)	61.632(H) * 109.6536(V) (5.0 inch)	mm	-
CTP View Area	62.16(H)*110.53(V)	mm	-
Driver element	TFT active matrix	-	-
Display colors	65K/262K/16.7M	colors	-
Number of pixels	480(RGB)*854	dots	-
TFT Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.1284 (H) x 0.1284 (V)	mm	-
Viewing angle	ALL	o'clock	-
TFT Controller IC	IL19806E	-	-
CTP Driver IC	GT911	-	-
Display mode	Transmissive/ Normally Black	-	-
Touch mode	5-point and Gestures	-	-
Operating temperature	-20∼+85	°C	-
Storage temperature	-40~+90	°C	

Mechanical Information

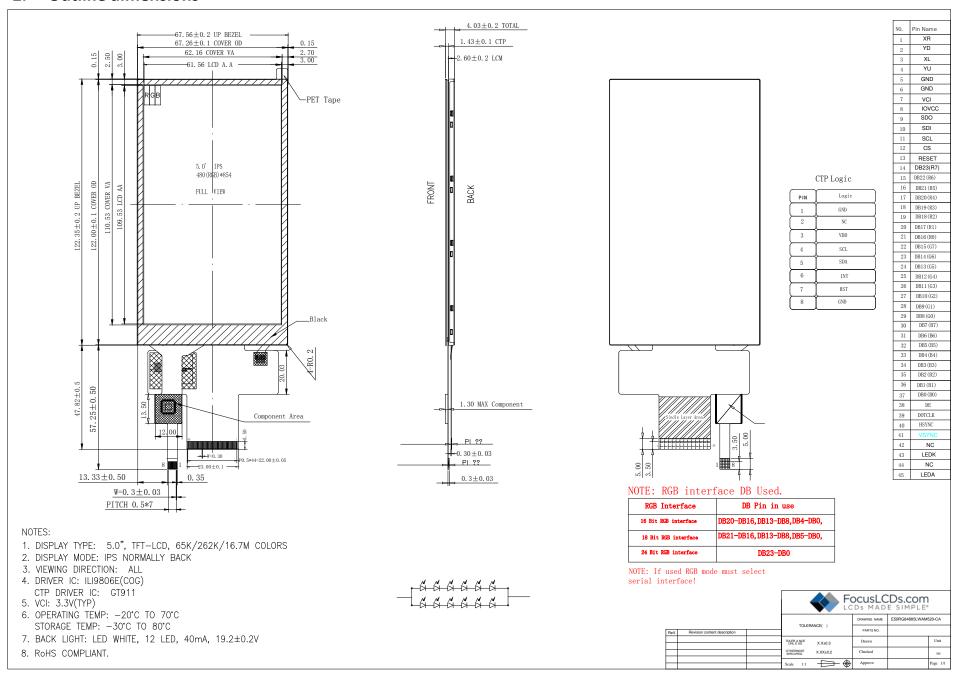
ltem		Min	Тур.	Max	Unit	Note
	Horizontal(H)		67.56		mm	-
Module size	Vertical(V)		122.35		mm	-
3120	Depth(D)		4.03		mm	-
Weight					g	-



1. Block Diagram



2. Outline dimensions





3. Input TFT Terminal Pin Assignment

Recommended TFT Connector: FH12S-45S-0.5SH(55) | Recommended CTP Connector: FH12-8S-0.5SH(55)

			(,					
NO.	Symbol	Description	1/0					
1	XR(NC)	Touch panel right glass terminal	A/D					
2	YD(NC)	Touch panel bottom film terminal	A/D					
3	XL(NC)	ouch panel left glass terminal						
4	YU(NC)	Touch panel top film terminal	A/D					
5	GND	Ground	Р					
6	GND	Ground	Р					
7	VCI	Supply voltage (3.3V)	Р					
8	IOVCC	I/O power supply voltage	Р					
9	SDO	SPI interface output pin. The data is output on the falling edge of the SCL signal. If not used leave this pin open.	0					
10	SDI	Data lane in 1 data lane serial interface. The data is latched on the rising edge of the SCL signal.	I					
11	SCL	Select "Data or Command" in the parallel interface. When D/CX = '1', data is selected. When D/CX = '0' command is selected. This pin is used as serial interface clock in 3-wire 9-bit/4-wire 8-bit serial data interface. Fix this pin to VCI or GND when not used.	1					
12	CS	Chip select input pin ("low" enable). Fix this pin to VCI or GND when not used.	I					
13	RESET	Reset pin. Setting either pin low initializes the LSI. Must be reset after power is supplied.	ı					
14-37	DB23-DB0	24-bit parallel bi-directional data bus for MCU system and RGB interface mode. Fix to GND when not in use.	1/0					
38	DE	Data enable signal for RGB interface operation. Fix to VCI or GND when not used.	I					
39	DOTCLK	Dot clock signal for RGB interface operation. Fix to VCI or GND when not used.	I					
40	HSYNC	Line synchronizing signal for RGB interface operation. Fix to VCI or GND when not used.	1					
41	VSYNC	Frame synchronizing signal for RGB interface operation. Fix to VCI or GND when not used.	ı					
42	NC							
43	LEDK	Cathode pin of backlight	Р					
44	NC							
45	LEDA	Anode pin of backlight	Р					

3.1 CTP

NO.	Symbol	Description	1/0
1	GND	Ground	Р
2	NC		
3	VDD	Supply voltage	Р
4	SCL	I2C clock input	1
5	SDA	I2C data input and output	1/0
6	INT	External interrupt to the host	1
7	RST	External reset, low is active	1
8	GND	Ground	Р



4. LCD Optical Characteristics

4.1 Optical Specifications

Item		Symbol	Condition	Min	Тур.	Max	Unit	Note
Contrast F	Ratio	CR	CR		800			(2)
	Rising	Tr			16	21	msec	(4)
Response time	Falling	TF			19	24	msec	(4)
Color Gai	mut	(%)			70		%	(5)
	White	W _X	Θ = Φ = 0		0.305			
	vviiite	W _Y	$\Theta = \Phi = 0$ Normal		0.340			
	Red	R _x	viewing angle					
Color Filter	Neu	R _Y						(5)(6)
Chromaticity	Green	G _X						
	Green	G _Y						
	Blue	B _X						
	Bide	B _Y						
	Hor.	ΘL			80			
Viewing angle	1101.	ΘR	Cr>10		80			4.34-3
viewing angle	Ver.	ΘU	CV>10		80			(1)(6)
	VCI.	ΘD			80			
Option View [Direction			FREE				(1)

4.2 Measuring Condition

VDD = 3.3V, IL = 20mA (Backlight current)

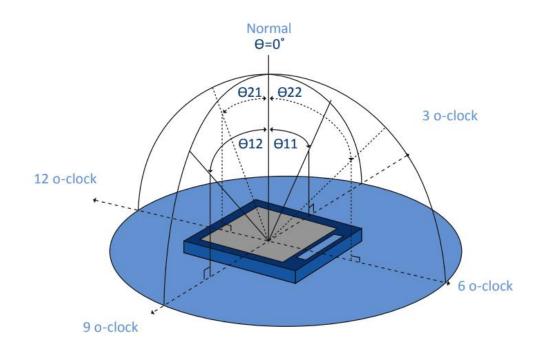
Ambient temperature: 25 ± 2°C

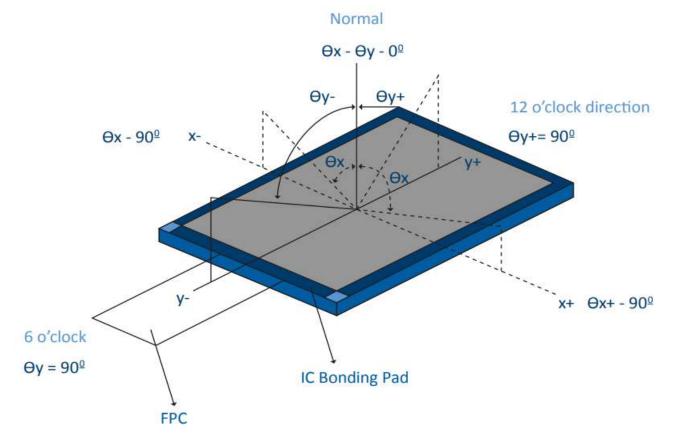
15min. warm-up time



Optical Specification Reference Notes:

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.



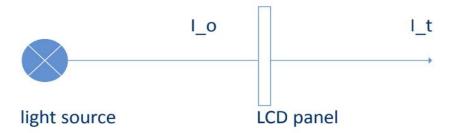




(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{Lw}{Ld}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving.



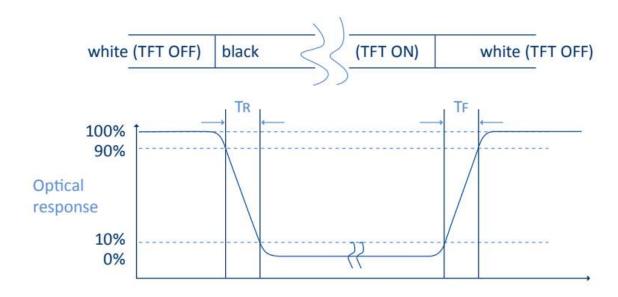
The transmittance is defined as:

$$Tr = \frac{It}{Io} x 100\%$$

Io = the brightness of the light source.

It = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.





(5) Definition of Color Gamut: Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y), G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics. The color chromaticity shall be calculated from the spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the panel.

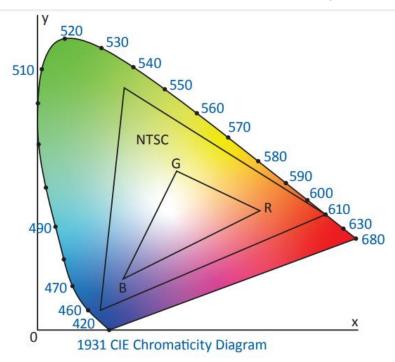
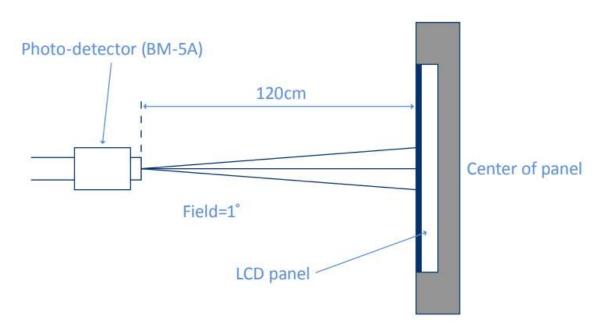


Fig. 1931 CIE chromacity diagram

Color gamut:
$$S = \frac{\text{Area of RGB triangle}}{\text{Area of NTSC triangle}} \times 100\%$$

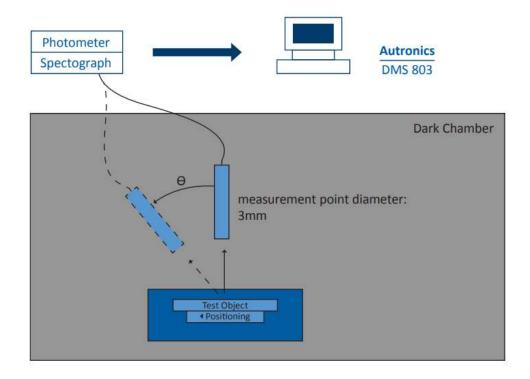
(6) Definition of Optical Measurement Setup:



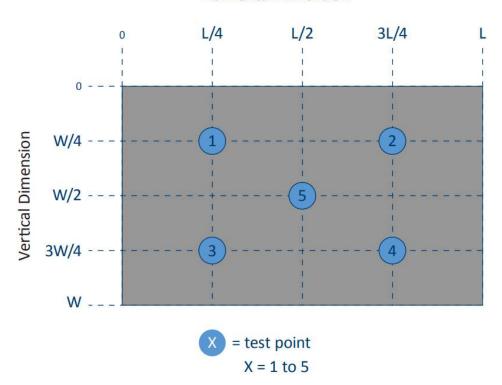


(6) Optical Measurement Setup Continued:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.



Horizontal Dimension





5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital Interface Supply Voltage	VDDIO	-0.3	4.6	V
Operating temperature	ТОР	-20	+70	°C
Storage temperature	TST	-30	+80	°C

NOTE: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VDD	2.5	2.8	3.6	V	
Digital Interface Supply Voltage	VDDIO	1.65	1.8	3.3	V	
Normal Mode Current Consumption	IDD		30		mA	
Level input voltage	VIH	0.7Vddio		VDDIO	V	
Level input voltage	VIL	-0.3		0.3VDDIO	V	
Level output voltage	VOH	0.8VDDIO		VDDIO	V	
Level output voltage	VOL	GND		0.2Vddio	V	



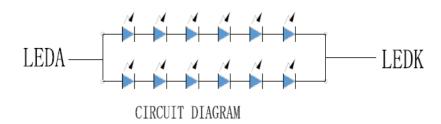
5.3 LED Backlight Characteristics

Item	Symbol	Min	Тур.	Max	Unit	Note
Forward Current	IF	30	40		mA	
Forward Voltage	VF		19.2		V	
LCM Luminance	LV		520		cd/m2	Note 3
LED lifetime	Hr	50000			hour	Note1 & 2
Uniformity	AVg	80			%	Note 3

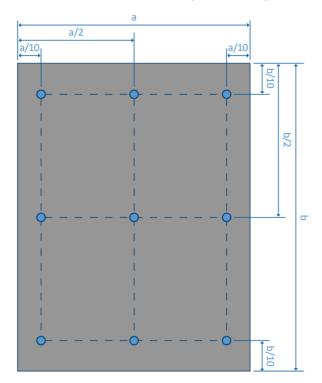
The back-light system is edge-lighting type with 12 chips White LED

Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition: $Ta=25\pm3$ °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=40mA. The LED lifetime could be decreased if operating IL is larger thar 40mA. The constant current driving method is suggested.



Note 3: Luminance Uniformity of these 9 points is defined as below:



Luminance =
$$(Total Luminance of 9 points)$$



6. AC Characteristic

6.1 Parallel 24/18/16-bit RGB Interface Timing Characteristics

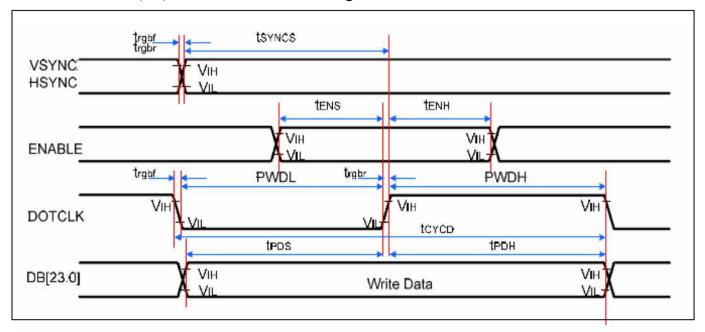


Figure 6.1: 24/18/16 Bits RGB Interface Timing Characteristics

Signal	Symbol	Parameter	Min	Max	Unit	Description
HSYNC/	Tsyncs	VSYNC/HSYNC Setup Time	5	-	ns	
VSYNC	Tsynch	VSYNC/HSYNC Hold Time	5	-	ns	
D.F.	Tens	Enable Setup Time	5	-	ns	
DE	TENH	Enable Hold Time	5	-	ns	
	PWDH	DOTCLK High-level Pulse Width	13	-	ns	16/18/24-bit bus RGB
DOTCLK	PWDL	DOTCLK Low-level Pulse Width	13	-	ns	interface mode
DOTCER	Tcycd	DOTCLK Cycle Time	28	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall Time	-	15	ns	
00[22.0]	TPDS	PD Data Setup Time	5	-	ns	
DB[23:0]	Тррн	PD Data Hold Time	5	-	ns	

Table 6.1: 24/18/16 Bits RGB Interface Timing Characteristics

Note: Ta= -30 to 70 $\,^{\circ}\!C$, IOVCC = 1.65V to 3.6V, VCI=2.5V to 3.6V, DGND=0V



6.2 DPI Interface TIming

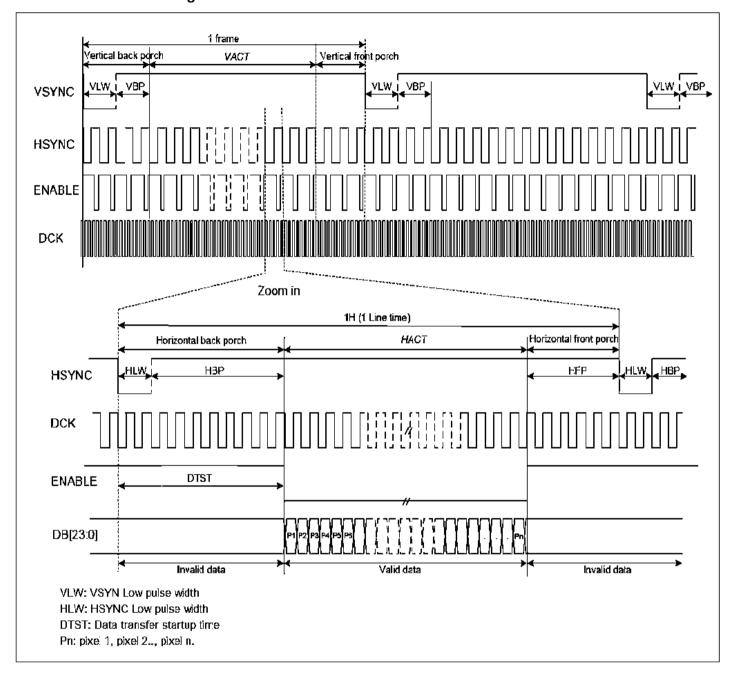


Figure 6.2: Clock and Data Input Timing Characteristics

Parameter	Symbols	Condition	Min	Тур.	Max	Units
Frame rate	FR		54		66	fps
Horizontal low pulse width	HLW		1			DOTCLK
Horizontal back porch	НВР		2		126	DOTCLK
Horizontal address	HACT			480		DOTCLK
Horizontal front porch	HFP		2			DOTCLK
Vertical low pulse width	VLW		1		126	Line
Vertical back porch	VBP		1		126	Line
Vertical address	VACT				864	Line
Vertical front porch	VFP		1		255	Line
Data clock	DCLK		16.6		41.7	MHz

Table 6.2: 24/18/16 Bits RGB Input Timing Characteristics



6.3 Display Serial Interface Characteristics (3-line SPI system)

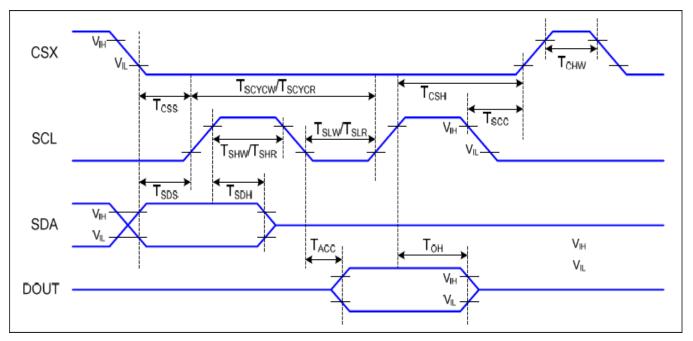


Figure 6.3: 3-line Serial Interface Timing Characteristics

VDDI = 1.64 to 3.3V, VDD = 2.4 to 3.3V, AGND=DGND=0V, $T\alpha$ =-30 to 70 $^{\circ}C$

Signal	Symbol	Parameter	Min	Max	Unit	Description
	T _{CSS}	Chip select setupt time (write)	15		ns	
	T _{CSH}	Chip select hold time (write)	15		ns	
CSX	T _{CSS}	Chip select setup time (read)	15		ns	
	T_{SCC}	Chip select hold time (read)	15		ns	
	T_CHW	Chip select "H" pulse width	40		ns	
	T _{SCYCW}	Serial clock cycle (write)	30		ns	
	T _{SHW}	SCL "H" pulse width (write)	10		ns	
SCL	T_SLW	SCL "L" width (write)	10		ns	
SCL	T _{SCYCR}	Serial clock cycle (read)	150		ns	
	T_{SHR}	SCL "H" pulse width (read)	60		ns	
	T_{SLR}	SCL "L" pulse width (read)	60		ns	
SDA/SDI	T_{SDS}	Data setup time (write)	10		ns	
(Input)	T_{SDH}	Data hold time (Write)	10			
SDA/SDO	T _{ACC}	Access time (read)	10	100	ns	For max CL=30pF
(DOUT)	T _{OH}	Output disable time (read)	15	100	ns	For min CL=8pF

Table 6.3: 3-line Serial Timing Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals



6.3 Reset Timing

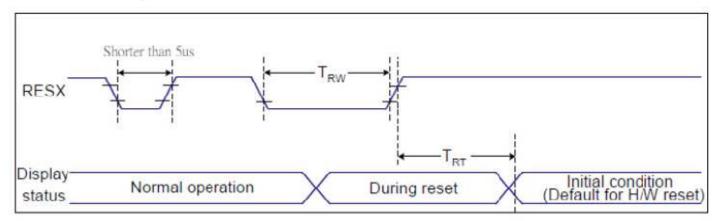


Figure 6.4: Reset Timing Diagram

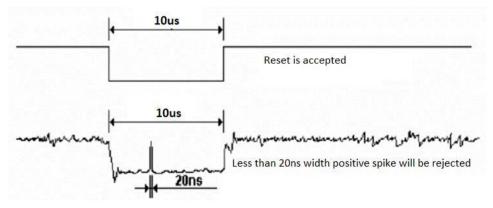
Related Pins	Symbol	Parameter	Min	Max	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TDT	Danet council	-	5 (Note 1,5)	ms
	TRT	Reset cancel		120 (Note 1, 6, 7)	ms

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action			
Shorter than 5us	Reset Rejected			
Longer than 9us	Reset			
Between 5us and 9 us	Reset starts			

- 3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



7. CTP Specification

7.1 Absolute Maximum Rating

Item	Symbol	Min	Max	Unit	Note
Power Supply Voltage	VDD	2.66	3.47	V	
Operating Temperature	Тор	-40	+85	°C	
Storage Temperature	Тѕт	-60	+125	°C	
Welding Temperature (10s)			300	°C	
ESD Protection Voltage (HB Model)			±2	kV	

7.2 DC Electrical Characteristics (TA=25°C)

Ambient temperature: 25 °C, AVDD=2.8V, VDDIO=1.8V or VDDIO=AVDD

	Anibient temperature. 25°C, AVDD-2.8V, VDDIO-1.8V 01 VDDIO-AVD						
Item	Min	Тур.	Max	Unit	Note		
Normal Mode Operating Current		8	14.5	mA			
Green Mode Operating Current		3.3		mA	-		
Sleep mode operating current	70	1	120	uA	1		
Doze Mode Operating Current		0.78		mA			
Digital Input Low Voltage (VIL)	-0.3		0.25VDDIO	V			
Digital Input High Voltage (VIH)	0.75VDDIO		VDDIO+0.3	V			
Digital Output Low Voltage (VOL)			0.15VDDIO	V			
Digital Output High Voltage (VOH)	0.85VDDIO			V			

7.3 AC Characteristics

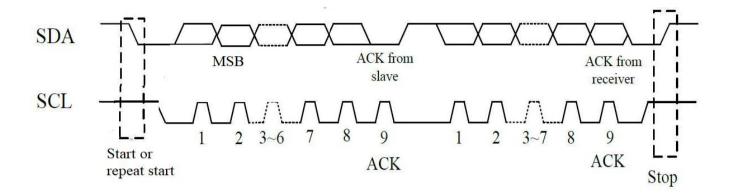
Ambient temperature: 25 °C, AVDD=2.8V, VDDIO=1.8V

Parameter	Min	Тур.	Max	Unit
OSC Oscillation Frequency	59	60	61	MHz
I/O Output Rise Time (low to high)	-	14	•	ns
I/O Output Rfall Time (high to low)	-	14	-	ns



7.3.1 I2C Interface Characteristics

GT911 provides a standard I2C interface for SCL and SDA to communicate with the host. GT911 always serves as slave device in the system with all communication being initialized by the host. It is recommended that transmission rate be kept at or below 400kbps. The figure shown below is the I2C timing:



Parameter	Symbols	Condition	Min	Max	Units
SCL low period	tlo		1.3		us
SCL high period	thi		0.6		us
SCL setup time for start condition	tst1		0.6		us
SCL setup time for stop condition	tst3		0.6		us
SCL hold time for start condition	thd1		0.6		us
SDA setup time	tst2		0.1		us
SDA hold time	thd2		0		us

Table 7.3.1: I2C AC Characteristics, 1.8V interface voltage, 400kbps transmission rate, 2k pull-up resistor

Parameter	Symbols	Condition	Min	Max	Units
SCL low period	tlo		1.3		us
SCL high period	thi		0.6		us
SCL setup time for start condition	t st1		0.6		us
SCL setup time for stop condition	tst3		0.6		us
SCL hold time for start condition	thd1		0.6		us
SDA setup time	t st2		0.1		us
SDA hold time	thd2		0		us

Table 7.3.2: I2C AC Characteristics, 3.3V interface voltage, 400kbps transmission rate, 2k pull-up resistor



GT911 supports two I2C slave addresses: 0xBA/0xBB and 0x28/0x29. The host can select the address by changing the status of Reset and INT pins during the power-on initialization phase. The configuration methods and timings are shown below:

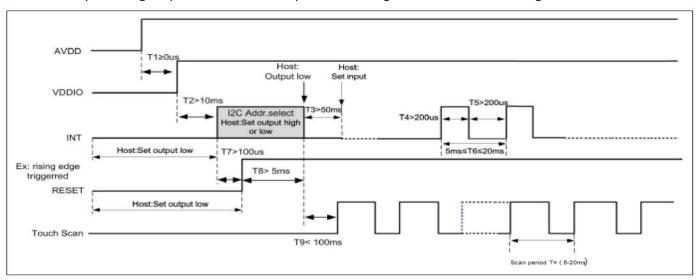


Figure 7..3.1: I2C Power on Timing

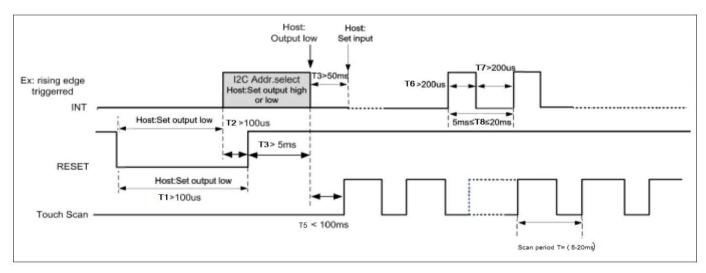


Figure 7.3.2: I2C Host Resetting Timing

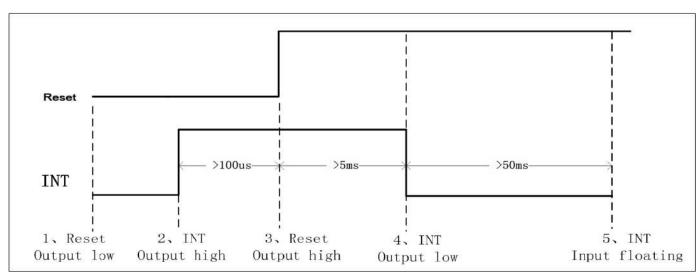


Figure 7.3.3: Setting Slave Address to 0x28/0x29 Timing



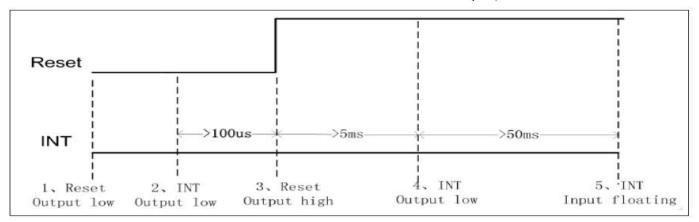


Figure 7.3.4: Setting Slave Address to 0xBA/0xBB Timing

Data Transmission (ex. 0xBA/0xBB)

Communication is always initiated by the host. Valid start condition is signaled by pulling SDA line from high to low when SCL is high. Data flow or address is transmitted after the start condition.

All slave devices connected to I2C bus should detect the 8-bit address issued after start condition and send the correct ACK. After receiving matching address, GT911 acknowledges by configuring SDA line as output port and pulling SDA line low during the ninth SCL cycle. When receiving unmatched address, namely not 0xBA or 0xBB, GT911 will stay in an idle state.

For data bytes on SDA, each of the 9 serial bits will be sent on nine SCL cycles. Each data byte consists of 8 valid data bits and one ACK or NACK bit sent by the recipient. The data transmission is valid when SCL line is high. When communication is completed the host will issue the stop condition. Stop condition implies the transition of SDA line from low to high when SCL is high.

Writing Data to GT911

The diagram displays the timing sequence of the host writing data onto GT911. First the host issues a start condition. The host sends 0xBA (address bits and R/W bit; R/W bit as 0 indicates write operation) to the slave device. After receiving ACK, the host sends the 16-bit register address (where writing starts) and the 8-bit data bytes (to be written onto the register)



The location of the register address pointer will automatically add 1 every write operation. When the host needs to perform write operations on a group of registers of continuous addresses it can write continuously. The write operation is terminated when the host issues the stop condition.

Reading Data from GT911

The diagram below is the timing sequence of the host reading data from GT911. The host issues the start condition and sends 0xBA (Address bits and R/W bit, R/W bit as 0 indicates write operation) to the slave device. After receiving ACK, the host sends the 16-bit register address (where reading starts) to the slave device. Then the host sets register addresses which need to be read.



The host issues the start condition once again and sends 0xBB (read operation). After receiving ACK, the host starts to read the data. GT911 also supports continuous read operation. When receiving a byte of data, the host sends an ACK signal indicating successful reception. After receiving the last byte of data, the host sends a NACK signal followed by a STOP condition which terminates communication.



8. Cautions and Handling Precautions

8.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static; it may cause damage to the CMOS ICs.
- 9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

8.2 Storage and Transportation.

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the TFT-LCD module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.